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# The SiD Digital ECal Based on Monolithic Active Pixel Sensors

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on behalf of the SiD MAPS Collaboration (M. Breidenbach, A. Dragone, A.Habib, L. Rota, M. Vassilev, C.Vernieri, J.B. et al.)

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# SiD Digital ECal Based on MAPS

- SiD upgrade now under development with
  25 x 100 μm<sup>2</sup> (or 25 x 50/25 μm<sup>2</sup>) digital pixels
  in electromagnetic calorimeter and tracker.
  - Replacing the ILC TDR ECal design using 13 mm<sup>2</sup> analog pixel sensors.
- Heat management is critical to success.



- \* How well can we measure energy and shower structure with this digital system:
  - \* Compared to SiD baseline with analog measurements?
  - \* Can the detailed structural measurements be used to improve measurement?
  - \* Would a neural net optimization offer an improvement?
- What are the limits of transverse separation and measurement? SiD Digital ECal
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#### Large area MAPS for SiD tracker & ECal

#### **Benefits of large-area MAPS:**

- Standard CMOS foundry, low resistivity: cost abla
- Sensing element and readout electronics on same die
  - In-pixel amplification: noise ↓, power ↓
  - No need for bump-bonding: cost au
- Area >  $5x20 \text{ cm}^2 \rightarrow$  enable O(1) m<sup>2</sup> modules

#### Several design challenges:

- Large on-die variations, mismatch
- Yield
- Stitching layout rules
- Distribution of power supply
- Distribution of global control signals/references



An example of the SiD Tracker and the ECal overall design

# Goals of R&D: find solutions and explore novel design techniques

SLAC

#### Main specifications for Large Area MAPS development

Parameter	Value	Notes	L. Rota		JLAC
Min Threshold	140 e-	0.25*MIP with 10 µm thick	epi layer		25 x 100 µm <sup>2</sup>
Spatial resolution	7 µm	In bend plane, based on S specs	iD tracker		ECal performance same as
Pixel size	25 x 100 µm <sup>2</sup>	Optimized for tracking(or 2	5x50/25 µm²)		50 x 50 µm²
Chip size	5 x 20 cm <sup>2</sup>	Requires stitching on 4 sid	es		
Chip thickness	300 µm	<200 µm for tracker. Could b EMCal to improve yield.	e 300 µm for		
Timing resolution (pixel)	~ ns	Bunch spacing: C <sup>3</sup> stricte 5.3->3.5 ns; ILC is 554 ns	st with		Ecal
Total lonizing Dose	100 kRads	Total lifetime dose, not a co	oncern		Tracker
Hit density / train	1000 hits / cm²				
Hits spatial distribution	Clusters	Due to jets			
Balcony size	1 mm	Only on one side, where w pads will be located.	ire-bonding	SiD Tracker and the ECa	
Power density	20 mW / cm <sup>2</sup>	Based on SiD tracker power consumption: 400W over 6	er <1 mV 57m <sup>2</sup> for 1%	V/cm <sup>2</sup> duty cycle	4



Current sensor optimization in TJ180/TJ65 nm process Effort to identify US foundry on going



Layout of SLAC prototype for WP1.2 2022 shared submission on TowerSemi 65nm

## Large Area MAPS - Highlights and Next Steps

#### Approach:

- Engaged with the scientific community to share know-how
- Focus on long-term R&D, targeting simultaneously:
  - ~ns timing resolution
  - Power consumption compatible with large area and low material budget
  - Fault-tolerant circuit strategies for wafer-scale MAPS

#### **Highlights:**

- Designed pixel architecture with binary readout optimized for linear colliders
- Submitted a small pixel matrix for fabrication on CERN WP1.2 shared run
- Architecture will allow us to evaluate technology in terms of defects and RTS Next steps:
- Evaluate performance of 1st SLAC prototype on TJ65nm (2023).
- New design combining O(ns) timing precision and low-power (2024/2025).
- Stretch Goals: design of a wafer-scale ASIC (2025/2026, design only) Engagement :
- Higgs Factory detector initiative R&D
- DRD 7.6 on common issues of power distributions compatible with stitching MAPS status @ LCWS 2024 Tuesday, 11am, Caterina Vernieri

SiD Digital ECal

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A. Habib *et al* 2024 *JINST* **19** C04033



# HCal **ECal**

- ECal module is built on first layer of HCal
- \* HCal module supports
  ECal module
- Note module overlap: No gaps; service cables at ends.



## i D•

#### Thermal Model for Heat Removal from SiD ECal



1 layer of 5 x 20 cm<sup>2</sup> MAPS sensors

- \* MAPS generates  $1 \mu W$ /pixel CW.
  - ~kW/m<sup>2</sup> (each sensor is 100 cm<sup>2</sup>)
- \* **Power pulsing** critical for heat management
  - \* ILC duty cycle ~0.5% (<10 W/m<sup>2</sup>)
  - \* CLIC/C^3 <0.01% (<1 W/m<sup>2</sup>)
- What is temperature rise (ΔT) on end opposite the cold plate?

#### Heat conduction from ECal sensor to cold plate



- \* First heat flows through 300  $\mu m~N_2$  to tungsten \*  $\Delta T << 1~K$
- Then heat flows thru tungsten to cold plate
  - \* Tungsten absorber lengths 0.5-1.0 m
  - \* Temperature rise is length dependent
- \* Duty cycle .0007% (C3/CLIC) ΔT ~ 0.5 2 K
- Duty cycle .005% (ILC)
   ΔT ~ 4 16 K
  - Without power pulsing temperature blows up and needs active cooling





SiD

# Ultimate Resolution (mips)

Mips(0.1 MeV) sumM2lin Events Entries 2000 140 695.6 Mean ll mips Std Dev 19.97 Resolution (%) = 2.9% Mip threshold = 0.1 MeV 100-Mean = 696.2 mlp Width = 19.1 mips 80 = 2.8% chi2/ndof = 63.4/35 = 1 10 GeV 60 10 2.8% 40 20 800 Mips 650 Mips(0.1 MeV)-hits sumM2hlin Pixels 2000 Entries 637 Mean 3% Std Dev 21.56 = 3.4% w/mips 100 aussian Fit Mean = 636.9 mlps Width = 21.0 mlps = 3.3% 10 GeV 2/ndot = 60 1/40 -60-3.3% 40 20-600 650 700 750 800 Mips/hits 550

mip counted once in a layer, when it enters sensor.

Gamma Resolution vs. Energy (B=5T)



# Resolution vs. Energy (hits & mips)

Gamma Resolution vs. Energy (B=5T)

**Resolution vs. Energy** (hits & mips)

5.8%

3.3%

120

100

60 E 40 F

20 9000

100

60 40 20





 Counting clusters should reduce hit fluctuations

tal ECal

Y-cord

# Resolution vs. Energy (hits/clusters/mips)





## $S_i D$ • Mips/cluster vs. shower R 10 GeV $\gamma$ s - 2000 showers



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## $10 \text{ GeV } \gamma \text{s} - 2000 \text{ showers}$

Clusters wt (radius,size) RadWt vs. mips



Apply weight to clusters:

RadWt =  $a \exp(-bR) + c$ 

a,b,c = f(CISz)

#### Resolution vs. Energy (hits/clusters/mips) Gamma Resolution vs. Energy (B=5T)





## TMVA Neural Net

TRAINING - 10 GeV 2000 events 2,502,000 hits 1,878,999 clusters

# Store model to file model.save('modelRegression%s.h5'%Efact) model.summary()

# Book methods

factory.BookMethod(dataloader, TMVA.Types.kPyKeras, 'PyKeras',

'H:!

V:VarTransform=D,G:FilenameModel=modelRegression%s.h5:FilenameTrainedModel= trainedModelRegression%s.h5:NumEpochs=20:BatchSize=32'%(Efact,Efact))

Neural net cluster weighting based on 1. Three input parameters = Cluster size,layer num,shower radius 2. Five input parameters = Add cluster length in Y and Z





# **Results: Energy Resolution**

Energy	1	2	5	10	20	50
clusters	13.8%	10.1%	6.6%	4.9%	3.7%	2.7%
wtd clusters	12.3%	8.8%	5.7%	4.4%	3.2%	2.2%
3 par TMVA	12.6%	9.5%	6.2%	4.4%	3.4%	2.2%
5 par TMVA	12.8%	9.4%	5.9%	4.3%	3.1%	2.2%

- \* Weight fits for 2, 10, 50 GeV; extrapolated for 1, 5, 20 GeV.
- NN optimized for each energy
- \* 3 par = cluster size, layer, radius
- \* 5 par = cluster size, layer, radius, dY, dZ

Weighted clusters already achieve performance of this neural net.



## Another topic: Potential impact of high granularity on particle flow measurements



#### Multi-shower of SiD MAPS compared to SiD TDR $40 \text{ GeV } \pi^0 \rightarrow \text{two } 20 \text{ GeV } \gamma$ 's





SiD TDR hexagonal sensors 13 mm<sup>2</sup> pixels

New SiD fine pixel sensors 25 µm x 100 µm pixels

2024



![](_page_26_Picture_0.jpeg)

#### $\gamma$ 's in jet / SiD baseline ECal (13mm<sup>2</sup> pixels)

![](_page_26_Figure_2.jpeg)

- 13 mm<sup>2</sup> pixels of analog SiD ECal
- 5000x granularity with digital MAPS ECal \*
- \* Future MAPS integration into full SiD simulation will define scale of improvement? 27

## • Conclusion

![](_page_27_Picture_1.jpeg)

- Application of monolithic active pixel sensors (MAPS) to SiD digital ECal offers excellent performance:
  - Energy measurement
  - \* Transverse energy containment & particle flow separation
- Well defined EM shower structure allows simple algorithmic optimization of energy measurement.
- \* An effort led by SLAC is progressing on the needed MAPS development.
- Neural nets have been studied to improve energy measurement:
  - \* They have not yet provided improvement over the "informed" algorithm.
- Passive heat management works for linear colliders given the very low duty cycle.
- \* The digital ECal will add valuable performance for particle flow reconstruction.
- \* Future simulation of full SiD detector with high granularity of MAPS ECal.

![](_page_28_Picture_0.jpeg)

#### Extras

![](_page_29_Figure_0.jpeg)